

10-12-06

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re: Appn. Ser. No. 10/733,672

Art Unit 2835

Filed 12/11/03

M.V. Datskovsky

Inventors L.S. Mok et al.

:Atty Dkt No. YOR920030186US1

For: CHIP PACKAGING MODULE WITH ACTIVE COOLING MECHANISMS

EXPRESS MAIL CERTIFICATE

Commissioner for Patents
P.O. Box 1450
Alexandria, Va. 22313- 1450
Sir:

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I hereby certify that the following attached paper or fee

Response to 9/18/06 Office Communication

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Alvin J. Riddles 10/12/06
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Sir:

Receipt of the 9/18/06 Office Communication, containing an assertion of abandonment resulting from a reply to a 12/21/05 Office Communication, assumed as not being received, is acknowledged herewith. However, the assertion is refuted by the attached receipt stamp indicating that a response was received 1/20/06.

The response included the response, an Information Disclosure Transmittal with reference copies and proposed replacement informal drawings transmitted under the Express Mail Label No. ED 882445249US.

Respectfully submitted,

Alvin J. Riddles 10/12/06

Alvin J. Riddles

Reg. No. 17862



PLEASE STAMP AND RETURN

Appn. Ser No. 10/733,672 : Art Unit. 2835

Filed 12/11/03 : Exr. M.V. Detskovskiy

Inventor L.S. Mok et al : Atty Dkt. YDR920030186 US1

RECEIVED IN THE U.S. PATENT AND TRADEMARK OFFICE

RESPONSE TO 12/21/05 OFFICE COMMUNICATION



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re. Appn. Ser. No. 10/733,672

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Art Unit 2835

Filed 12/11/03

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Examiner M.V. Dotskoyskiy

Inventors L.S.Mok et al.

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Atty. Dkt. No. YOR920030186US1

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P.O. Box 1450
Alexandria Va. 22313-1450
Sir:

Express Mail Label No. ED 882445249 US
Date of Deposit 1/20/06

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Response to 12/21/05, Office Communication - Requirement for restriction,

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Replacement Informal Drawing Submission - 9 sheets

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Alvin J. Riddles

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Alvin J. Riddles 1/20/06

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